

Arijit Roy

List of Publications by Year in descending order

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23
papers

453
citations

1040056

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794594

19
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23
all docs

23
docs citations

23
times ranked

287
citing authors

#	ARTICLE	IF	CITATIONS
1	Electromigration in ULSI interconnects. Materials Science and Engineering Reports, 2007, 58, 1-75.	31.8	198
2	Investigation of the effect of temperature and stress gradients on accelerated EM test for Cu narrow interconnects. Thin Solid Films, 2006, 504, 288-293.	1.8	62
3	Probing into the asymmetric nature of electromigration performance of submicron interconnect via structure. Thin Solid Films, 2007, 515, 3867-3874.	1.8	28
4	Experimental investigation on the impact of stress free temperature on the electromigration performance of copper dual damascene submicron interconnect. Microelectronics Reliability, 2006, 46, 1652-1656.	1.7	23
5	Very high current density package level electromigration test for copper interconnects. Journal of Applied Physics, 2008, 103, 093707.	2.5	22
6	Application of gamma distribution in electromigration for submicron interconnects. Journal of Applied Physics, 2007, 102, .	2.5	20
7	Effect of test condition and stress free temperature on the electromigration failure of Cu dual damascene submicron interconnect line-via test structures. Microelectronics Reliability, 2005, 45, 1443-1448.	1.7	18
8	An efficient method of detection of COVID-19 using Mask R-CNN on chest X-Ray images. AIMS Biophysics, 2021, 8, 281-290.	0.6	16
9	Electromigration in damascene copper interconnects of line width down to 100 nm. Semiconductor Science and Technology, 2006, 21, 1369-1372.	2.0	15
10	Design of efficient loadcell for measurement of mechanical impact by piezoelectric PVDF film sensor. AIP Advances, 2016, 6, 095122.	1.3	9
11	A transmon-based quantum half-adder scheme. Progress of Theoretical and Experimental Physics, 2015, 2015, 093A02.	6.6	8
12	Effect of vacuum break after the barrier layer deposition on the electromigration performance of aluminum based line interconnects. Microelectronics Reliability, 2005, 45, 1449-1454.	1.7	5
13	Fabrication and characterization of copper interconnects of line-width down to 100nm using a specially designed phase shift mask. Microelectronic Engineering, 2014, 113, 152-156.	2.4	5
14	An experimental method of bioimpedance measurement and analysis for discriminating tissues of fruit or vegetable. AIMS Biophysics, 2020, 7, 41-53.	0.6	5
15	Experimenting and modeling of catastrophic failure in electromigration-induced resistance degradation for deep submicron dual-damascene copper interconnects. Solid-State Electronics, 2018, 148, 7-15.	1.4	4
16	Measurement of bioimpedance and application of Cole model to study the effect of moisturizing cream on human skin. AIMS Biophysics, 2020, 7, 362-379.	0.6	4
17	Electromigration in width transition copper interconnect. Microelectronics Reliability, 2009, 49, 1086-1089.	1.7	3
18	Dynamics of electromigration induced void in submicron Cu interconnects. , 2011, , .		3

#	ARTICLE	IF	CITATIONS
19	Microstructure Measurement Techniques for Studying Electromigration in ULSI Interconnects. Critical Reviews in Solid State and Materials Sciences, 2016, 41, 159-191.	12.3	3
20	Multiple data access via a common cavity bus in circuit QED. International Journal of Circuit Theory and Applications, 2017, 45, 970-988.	2.0	1
21	Inadequacy of Markov Model in Modeling of Electromigration-Induced Resistance Degradation. , 2018, , .		1
22	Room temperature observation of point defect on gold surface using thermovoltage mapping. Microelectronics Reliability, 2007, 47, 1580-1584.	1.7	0
23	Proposal of a transmon-based high bandwidth quantum router. , 2017, , .		0